

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5536831

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEI-CHIH CHEN	05/07/2019
HUNG-JUI KUO	05/07/2019
YU-HSIANG HU	05/07/2019
SIH-HAO LIAO	05/07/2019
PO-HAN WANG	05/07/2019
YUNG-CHI CHU	05/07/2019
HUNG-CHUN CHO	05/07/2019
RECEIVING PARTY DATA	
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State/Country:	TAIWAN
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16413591
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NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	05/23/2019

Total Attachments: 4

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

PACKAGE STRUCTURE AND METHOD OF MANUFACTURING THE SAME

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number

_____ Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Taiwan Semiconductor Manufacturing Co., Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P20181114US00
81461-US-PA

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Wei-Chih Chen Date: 5.7. 2019

Legal Name of Sole or First Inventor: **Wei-Chih Chen**

Residence: Taipei City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Hung-Jui Kuo Date: 2019 05/07

Legal Name of Additional Joint Inventor, if any: **Hung-Jui Kuo**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Yu-Hsiang Hu Date: 2019. 05. 07

Legal Name of Additional Joint Inventor, if any: **Yu-Hsiang Hu**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Sih-Hao Liao Date: 5.7. 2019

Legal Name of Additional Joint Inventor, if any: **Sih-Hao Liao**

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Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Po-Han Wang Date: 5.7. 2019

Legal Name of Additional Joint Inventor, if any: **Po-Han Wang**

Residence: Hsinchu City, Taiwan

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Yung-Chi, Chu Date: 2019/05/07

Legal Name of Additional Joint Inventor, if any: **Yung-Chi Chu**

Residence: Kaohsiung City, Taiwan

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Signature: Hung-Chun Cho Date: 2019/05/07

Legal Name of Additional Joint Inventor, if any: **Hung-Chun Cho**

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